



## 2013 International Semiconductor Conference Dresden - Grenoble (ISCDG)

alternating venue in Dresden (Germany) and Grenoble (France) every other year

Technology, Design, Packaging, Simulation and Test  
International Conference, Short Course and Table Top Exhibition

September, 26 - 27, 2013 - Dresden, Germany



„Meet Leading Players and Experts at the ISCDG 2013 in Dresden, Germany“. The Largest Microelectronic Center in Europe!

Grenoble and Dresden are the two major European Semiconductor Research, Development and Production sites. In the preceeding editions of 2009 and 2011, the conference was named “Semiconductor Conference Dresden”. The objective of the IS-CDG is to enhance the visibility of international excellence of the European players. The first edition of ISCDG was held in 2012 in Grenoble. The 2013 ISCDG will be held in Dresden. The venue will be alternating in Dresden and Grenoble every other year.

### Call for Papers

Main areas covered by the conference: Materials, devices and systems science, engineering and architectures and their characterization available soon

#### Papers are requested in the following areas:

- **Integrated Circuit and System Design**  
Mixed-signal, analog and digital circuits and systems for high speed and/or low power consumption, adaptive power management, RF up to sub-THz, low costs, and advanced performance and density, circuits in More than Moore and Beyond Moore technologies. Manufacturing challenges (cost and cycle time reduction, test, wafer-prime-production etc.), ...
- **More Moore and Beyond Moore Devices Technologies and Architectures**  
Ultimate CMOS (silicon and IV-IV strained alloys on insulator, multi-gate and channel transistors, III-V channels), nanowires, thin films dielectrics: high-k and low-k; nano-materials; advanced on-chip interconnects; Beyond Moore: TunFETs, carbon electronics,...
- **Memory Technologies**  
Stand alone and Embedded Memory Technologies, new memory technologies: RRAMs, CBRAMs, MRAMs, 1T DRAM, ...
- **More than Moore Technologies**  
MEMS, NEMS, power devices, RF and analog passive components (MIM, filters, supercapacitors, inductances,...), spintronics based devices, bio sensors, imagers, thermoelectric, energy harvesting, ...
- **Interconnection and Packaging Technologies**  
3D and novel interconnects, wire bonding, flip chip, solder replacement flip chip, under bump metallurgy, high density substrates, New packaging technologies for single chip, multi-chip, wafer level, power and stacked-die packages, wafer bumping and thinning, ...
- **Optical Devices and Photonics**  
Optical component assemblies, electro-optical modules, waveguides, silicon based photonic devices, organic devices, optical materials, ...
- **Organic and Flexible Electronics**  
Polymer and organic, printed electronics, organic PV and PV in organic, OLEDs, ...
- **Characterization, Quality and Reliability**  
Electrical characterization, testing strategies and protocols, physical characterization for process development and process control, component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testing and models, component and system qualification.
- **Modeling and Simulation**  
EDA, TCAD, electrical, thermal, thermo-mechanical, reliability, optical, modeling and simulation for devices, component and system level applications, ...



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deadline extended!  
June 09, 2013

### Key Dates:

Paper submission deadline

~~April 30, 2013~~

Paper acceptance

June 15, 2013

Deadline for early bird registration

August 15, 2013

(accommodation, conference and short course fees)

### Submit Paper

Submission of papers in the areas mentioned above are encouraged and solicited to describe original work.

The paper must include the purpose, applications, results, comparison with the state-of-the-art, conclusions, visualizing pictures and key references.

All conference papers will be included in IEEEExplore.

Papers will be presented at the conference as talks or posters.

» Please send your proposal to [paper-iscdg@gerotron.com](mailto:paper-iscdg@gerotron.com)

#### Guidelines for submitted papers:

- Papers have to be formatted in accordance with the [IEEE – Manuscript Templates for Conference Proceedings](#)
- Contributions can only be accepted in English language
- Paper length: min. one page with text, second page with figures.  
After conformation of acceptance 3 - 4 pages for the IEEE explorer
- File format: pdf, file size max. 5 MB

In addition we need the ISCDG Paper Submission Form

download

[http://iscdg.org/ISCDG\\_2013\\_paper\\_submission\\_form.doc](http://iscdg.org/ISCDG_2013_paper_submission_form.doc)

Please fill out the form below and send this document together with your paper submission to us.

» Official website: [www.iscdg.org](http://www.iscdg.org)

#### General Management & Publicity:

GEROTRON Communication GmbH

Contact: Georg Schmidt

Bunsenstr. 5/II

82152 Martinsried, Germany

E-mail: [georg.schmidt@gerotron.com](mailto:georg.schmidt@gerotron.com)

Phone: +49 (0)89 189 08 17 80

Fax: +49 (0)89 89 55 69 29

[www.gerotron.com](http://www.gerotron.com)

#### Co-Management:

INSIGHT OUTSIDE

Phone: +33 (0)4 38 38 18 22 / +33 (0)6 10 80 31 98

Fax: +33 4 38 38 18 19

E-mail: [iscdg2012@insight-outside.fr](mailto:iscdg2012@insight-outside.fr)

[www.insight-outside.fr](http://www.insight-outside.fr)



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